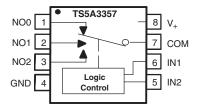
#### **FEATURES**

- · Specified Break-Before-Make Switching
- Low ON-State Resistance
- High Bandwidth
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)

#### **APPLICATIONS**

- Cell Phones
- PDAs
- Portable Instrumentation

#### SC-70 (DCU) PACKAGE (TOP VIEW)



#### **FUNCTION TABLE**

IN1	IN2	COM TO NO0	COM TO NO1	COM TO NO2
L	L	OFF	OFF	OFF
Н	L	ON	OFF	OFF
L	Н	OFF	ON	OFF
Н	Н	OFF	OFF	ON

#### **DESCRIPTION/ORDERING INFORMATION**

The TS5A3357 is a high-performance, single-pole triple throw (SP3T) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers a low ON-state resistance and low input/output capacitance and, thus, causes a very low signal distortion. The break-before-make feature allows transferring of a signal from one port to another, with a minimal signal distortion. This device also offers a low charge injection which makes this device suitable for high-performance audio and data acquisition systems.

#### Summary of Characteristics(1)

Configuration	Triple 3:1 Multiplexer/ Demultiplexer (1 × SP3T)				
Number of channels	1				
ON-state resistance (r <sub>on</sub> )	5 Ω				
ON-state resistance match (Δr <sub>on</sub> )	0.1 Ω				
ON-state resistance flatness (r <sub>on(flat)</sub> )	6.5 Ω				
Turn-on/turn-off time (t <sub>ON</sub> /t <sub>OFF</sub> )	6.5 ns/3.7 ns				
Break-before-make time (t <sub>BBM</sub> )	0.5 ns				
Charge injection (Q <sub>C</sub> )	3.4 pC				
Bandwidth (BW)	334 MHz				
OFF isolation (O <sub>ISO</sub> )	-82 dB at 10 MHz				
Crosstalk (X <sub>TALK</sub> )	-62 dB at 10 MHz				
Total harmonic distortion (THD)	0.05%				
Leakage current (I <sub>COM(OFF)</sub> )	±1 μA				
Package option	8-pin DCU (US8)				

(1) 
$$V_+ = 5 \text{ V}, T_A = 25^{\circ}\text{C}$$



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING(3)	
–40°C to 85°C	SOT (SC-70) - DCU	Tape and reel	TS5A3357DCUR	JA9_	

- (1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (3) DCU: The actual top-side marking has one additional character that designates the assembly/test site.

## **ABSOLUTE MINIMUM AND MAXIMUM RATINGS**(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{+}$	Supply voltage range <sup>(3)</sup>		-0.5	6.5	V
$V_{NO} \ V_{COM}$	Analog voltage range (3)(4)(5)		-0.5	V <sub>+</sub> + 0.5	V
I <sub>K</sub>	Analog port diode current	$V_{NO}$ , $V_{COM} < 0$ or $V_{NO}$ , $V_{COM} > V_{+}$	-50	50	mA
I <sub>NO</sub> I <sub>COM</sub>	On-state switch current	$V_{NO}$ , $V_{COM} = 0$ to $V_{+}$	-100	100	mA
$V_{I}$	Digital input voltage range (3)(4)		-0.5	6.5	V
$I_{IK}$	Digital input clamp current	V <sub>I</sub> < 0	-50		mA
I <sub>+</sub>	Continuous current through V <sub>+</sub>			100	mA
$I_{GND}$	Continuous current through GND		-100	100	mA
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

- (2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum.
- (3) All voltages are with respect to ground, unless otherwise specified.
- (4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 5) This value is limited to 5.5 V maximum.

#### PACKAGE THERMAL IMPEDANCE

		MAX	UNIT
$\theta_{JA}$	Package thermal impedance <sup>(1)</sup>	165	°C/W

(1) The package thermal impedance is calculated in accordance with JESD 51-7.

## **ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY**(1)

 $V_{+} = 4.5 \text{ V}$  to 5.5 V,  $T_{A} = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	ONDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	$V_{COM}, V_{NO}$					0		V <sub>+</sub>	V
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NO} \le V_+,$ $I_{COM} = -30 \text{ mA},$	Switch ON, See Figure 13	Full	4.5 V			15	Ω
		$V_{NO} = 0,$		25°C			5	7	
		I <sub>COM</sub> = 30 mA		Full				7	
ON-state resistance	r <sub>on</sub>	$V_{NO} = 2.4 \text{ V},$	Switch ON,	25°C	4.5 V		6	12	Ω
ON State resistance	on	$I_{COM} = -30 \text{ mA}$	See Figure 13	Full	4.5 V			12	32
		$V_{NO} = 4.5 \text{ V},$		25°C			7	15	
		$I_{COM} = -30 \text{ mA}$		Full				15	
ON-state resistance match between channels	Δr <sub>on</sub>	$V_{NO} = 3.15 \text{ V},$ $I_{COM} = -30 \text{ mA},$	Switch ON, See Figure 13	25°C	4.5 V		0.1		Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le V_{NO} \le V_{+},$ $I_{COM} = -30 \text{ mA},$	Switch ON, See Figure 13	25°C	5 V		6.5		Ω
NO	ı	$V_{NO} = 0$ to $V_+$ ,	Switch OFF,	25°C	5.5 V	-0.1		0.1	^
OFF leakage current	I <sub>NO(OFF)</sub>	$V_{COM} = V_{+}$ to 0	See Figure 14	Full	5.5 V	-1		1	μΑ
COM		$V_{COM} = 0 \text{ to } V_+,$	Switch OFF,	25°C	0	-0.1		0.1	μA
OFF leakage current	I <sub>COM(OFF)</sub>	$V_{NO} = V_{+}$ to 0,	See Figure 14	Full	U	-1		1	μА
NO		$V_{NO} = 0$ to $V_+$ ,	Switch ON,	25°C	5.5 V	-0.1		0.1	μA
ON leakage current	I <sub>NO(ON)</sub>	V <sub>COM</sub> = Open,	See Figure 14	Full	3.3 V	-1		1	μА
СОМ	laa.wa.s	V <sub>NO</sub> = Open,	Switch ON,	25°C	5.5 V	-0.1		0.1	μA
ON leakage current	I <sub>COM(ON)</sub>	$V_{COM} = 0$ to $V_+$ ,	See Figure 14	Full	J.J V	-1		1	μΛ
<b>Digital Control Input</b>	s (IN1, IN2) <sup>(</sup>	2)							
Input logic high	$V_{IH}$			Full		$V_{+} \times 0.7$		5.5	V
Input logic low	$V_{IL}$			Full		0		$V_{+} \times 0.3$	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	5.5 V			0.1	μΑ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

<sup>(2)</sup> All unused digital inputs of the device must be held at V<sub>+</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## **ELECTRICAL CHARACTERISTICS FOR 5-V SUPPLY (continued)**

 $V_{+}$  = 4.5 V to 5.5 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	NDITIONS	TA	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic	"	,		'					
Towns on these		$V_{NO} = V_{+}$ or GND,	$C_1 = 50 \text{ pF},$	25°C	5 V	1.5		6.5	
Turn-on time	t <sub>ON</sub>	$R_L = 500 \Omega$ ,	See Figure 16	Full	4.5 V to 5.5 V	1.5		7	ns
T		$V_{NO} = V_{+}$ or GND,	$C_1 = 50 \text{ pF},$	25°C	5 V	0.8		3.7	
Turn-off time	t <sub>OFF</sub>	$R_L = 500 \Omega$	See Figure 16	Full	4.5 V to 5.5 V	0.8		7	ns
Break-before-	_	$V_{NO} = V_+$	$C_{L} = 50 \text{ pF},$	25°C	5 V	0.5			
make time	t <sub>BBM</sub>	$R_L = 50 \Omega$ ,	See Figure 17	Full	4.5 V to 5.5 V	0.5			ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $C_L = 0.1 \text{ nF},$	See Figure 21	25°C	5 V		3.4		рС
NO OFF capacitance	C <sub>NO(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 15	25°C	5 V		4.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 15	25°C	5 V		10.5		pF
NO ON capacitance	C <sub>NO(ON)</sub>	$V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 15	25°C	5 V		17		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 15	25°C	5 V		17		рF
Digital input capacitance	Cı	$V_I = V_+ \text{ or GND},$	See Figure 15	25°C	5 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 18	25°C	4.5 V to 5.5 V		334		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 19	25°C	4.5 V to 5.5 V		-82		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 20	25°C	4.5 V to 5.5 V		-62		dB
Supply	•			1					
Positive supply			Switch ON or	25°C	25°C			1	^
current	I <sub>+</sub>	$V_I = V_+ \text{ or GND},$	OFF	Full				10	μΑ

## TS5A3357 SINGLE 5-Ω SP3T ANALOG SWITCH 5-V/3.3-V 3:1 MULTIPLEXER/DEMULTIPLEXER

SCDS177A-OCTOBER 2004-REVISED DECEMBER 2007

## **ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY<sup>(1)</sup>**

 $V_{+} = 3 \text{ V}$  to 3.6 V,  $T_{A} = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST C	ONDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP MAX	UNIT
Analog Switch								
Analog signal range	$V_{COM}, V_{NO}$					0	V <sub>+</sub>	V
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NO} \le V_{+},$ $I_{COM} = -24 \text{ mA},$	Switch ON, See Figure 13	Full	3 V		25	Ω
		$V_{NO} = 0 V$ ,		25°C			6.5 9	
ON-state resistance	_	$I_{COM} = 24 \text{ mA}$	Switch ON,	Full	3 V		9	Ω
ON-State resistance	r <sub>on</sub>	$V_{NO} = 3 V$ ,	See Figure 13	25°C	3 V		9 20	12
		$I_{COM} = -24 \text{ mA}$		Full			20	
ON-state resistance match between channels	$\Delta r_{ m on}$	$V_{NO} = 2.1 \text{ V},$ $I_{COM} = -24 \text{ mA},$	Switch ON, See Figure 13	25°C	3 V		0.1	Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le V_{NO} \le V_+,$ $I_{COM} = -24 \text{ mA},$	Switch ON, See Figure 13	25°C	3.3 V		13.5	Ω
NO		$V_{NO} = 0$ to $V_{+}$	Switch OFF,	25°C	3.6 V	-0.1	0.1	
OFF leakage current	I <sub>NO(OFF)</sub>	$V_{COM} = V_{+}$ to 0	See Figure 14	Full	3.6 V	-1	1	μΑ
СОМ	1	$V_{COM} = 0 \text{ to } V_+,$	Switch OFF,	25°C	3.6 V	-0.1	0.1	
OFF leakage current	I <sub>COM(OFF)</sub>	$V_{NO} = V_{+}$ to 0,	See Figure 14	Full	3.6 V	-1	1	μΑ
NO		$V_{NO} = 0$ to $V_{+}$	Switch ON,	25°C	3.6 V	-0.1	0.1	
ON leakage current	I <sub>NO(ON)</sub>	$V_{COM} = V_{+}$ to 0,	See Figure 14	Full	3.6 V	-1	1	μΑ
СОМ		V <sub>NO</sub> = Open,	Switch ON,	25°C	2.6.1/	-0.1	0.1	^
ON leakage current	I <sub>COM(ON)</sub>	$V_{COM} = 0$ to $V_+$ ,	See Figure 14	Full	3.6 V	-1	1	μΑ
Digital Control Input	s (IN1, IN2)	(2)						
Input logic high	$V_{IH}$			Full		$V_+ \times 0.7$	5.5	V
Input logic low	V <sub>IL</sub>			Full		0	$V_+ \times 0.3$	V
Input leakage		V		25°C	0.01/	-1	0.1	
current	I <sub>IH</sub> , I <sub>IL</sub>	$V_1 = 5.5 \text{ V or } 0$		Full	3.6 V		1	μΑ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

<sup>(2)</sup> All unused digital inputs of the device must be held at V<sub>+</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



## **ELECTRICAL CHARACTERISTICS FOR 3.3-V SUPPLY (continued)**

 $V_{+} = 3 \text{ V to } 3.6 \text{ V}, T_{A} = -40^{\circ}\text{C to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$ 

PARAMETER	SYMBOL	TEST C	ONDITIONS	TA	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic	"				-11				
		$V_{NO} = V_{+}$ or	$C_{L} = 50 \text{ pF},$	25°C	3.3 V	2		9.5	
Turn-on time	t <sub>ON</sub>	GND, $R_L = 500 \Omega$ ,	See Figure 16	Full	3 V to 3.6 V	2		11	ns
		$V_{NO} = V_{+}$ or	$C_{L} = 50 \text{ pF},$	25°C	3.3 V	1.3		5.1	
Turn-off time	t <sub>OFF</sub>	GND, $R_L = 500 \Omega$ ,	See Figure 16	Full	3 V to 3.6 V	1.5		5.5	ns
Break-before-		$V_{NO} = V_+,$	$C_L = 50 \text{ pF},$	25°C	3.3 V	0.5			
make time	t <sub>BBM</sub>	$R_L = 50 \Omega$ ,	See Figure 17	Full	3 V to 3.6 V	0.5			ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $C_L = 0.1 \text{ nF},$	See Figure 21	25°C	3.3 V		1.75		рС
NO OFF capacitance	C <sub>NO(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 15	25°C	3.3 V		4.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 15	25°C	3.3 V		10.5		pF
NO ON capacitance	C <sub>NO(ON)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 15	25°C	3.3 V		17		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 15	25°C	3.3 V		17		pF
Digital input capacitance	Cı	$V_I = V_+ \text{ or GND},$	See Figure 15	25°C	3.3 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 18	25°C	3 V to 3.6 V		327		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 19	25°C	3 V to 3.6 V		-82		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 20	25°C	3 V to 3.6 V		-62		dB
Supply				•					Į.
Positive supply	I <sub>+</sub>	$V_1 = V_+$ or GND,	Switch ON or OFF	25°C	3.6 V			1	μА
current	1+	$v_1 = v_+ \text{ or GND},$	SWILCH ON OF OFF	Full	3.0 V			10	μΑ

## **ELECTRICAL CHARACTERISTICS FOR 2.5-V SUPPLY<sup>(1)</sup>**

 $V_{+}$  = 2.3 V to 2.7 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	ONDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									•
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub>					0		V <sub>+</sub>	V
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NO} \le V_{+},$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	Full	2.3 V			50	Ω
		$V_{NO} = 0 V$ ,		25°C			8	12	
ON-state	_	$I_{COM} = 8 \text{ mA}$	Switch ON,	Full	2.3 V			12	Ω
resistance	r <sub>on</sub>	$V_{NO} = 2.3 V,$	See Figure 13	25°C	2.3 V		11	30	12
		$I_{COM} = -8 \text{ mA}$		Full				30	
ON-state resistance match between channels	Δr <sub>on</sub>	$V_{NO} = 1.8 \text{ V},$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C	2.3 V		0.3		Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le V_{NO} \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C	2.5 V		39		Ω
NO	_	$V_{NO} = 0$ to $V_+$	Switch OFF,	25°C		-0.1		0.1	
OFF leakage current	I <sub>NO(OFF)</sub>	$V_{COM} = V_+ \text{ to } 0$	See Figure 14	Full	2.7 V	-1		1	μΑ
СОМ		$V_{COM} = 0 \text{ to } V_+,$	Switch OFF,	25°C		-0.1		0.1	
OFF leakage current	I <sub>COM(OFF)</sub>	$V_{NO} = V_{+}$ to 0,	See Figure 14	Full	2.7 V	-1		1	μΑ
NO		$V_{NO} = 0$ to $V_{+}$	Switch ON,	25°C		-0.1		0.1	
ON leakage current	I <sub>NO(ON)</sub>	$V_{COM} = V_+ \text{ to } 0,$	See Figure 14	Full	2.7 V	-1		1	μΑ
СОМ	_	V <sub>NO</sub> = Open,	Switch ON,	25°C		-0.1		0.1	
ON leakage current	I <sub>COM(ON)</sub>	$V_{COM} = 0 \text{ to } V_+,$	See Figure 14	Full	2.7 V	-1		1	μА
Digital Control Inp	uts (IN1, IN2	) <sup>(2)</sup>							
Input logic high	$V_{IH}$			Full		$V_+ \times 0.75$		5.5	V
Input logic low	V <sub>IL</sub>			Full		0		$V_{\text{+}} \times 0.25$	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	2.7 V			0.1	μΑ

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

<sup>(2)</sup> All unused digital inputs of the device must be held at V<sub>+</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



## **ELECTRICAL CHARACTERISTICS FOR 2.5-V SUPPLY (continued)**

 $V_{+}$  = 2.3 V to 2.7 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	ONDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic	"								
Turn-on time	t <sub>ON</sub>	$V_{NO} = V_{+}$ or GND,	C <sub>L</sub> = 50 pF, See Figure 16	25°C	2.5 V	3		15	ns
		$R_L = 500 \Omega$ ,	See Figure 10	Full	2.3 V to 2.7 V	3		16.5	
Turn-off time		$V_{NO} = V_{+}$ or GND,	$C_{L} = 50 \text{ pF},$	25°C	2.5 V	2		7.2	
rum-on ume	t <sub>OFF</sub>	$R_L = 500 \Omega$	See Figure 16	Full	2.3 V to 2.7 V	2		7.8	ns
Break-before-	t	$V_{NO} = V_+,$	C <sub>L</sub> = 50 pF,	25°C	2.5 V	0.5			ns
make time	t <sub>BBM</sub>	$R_L = 50 \Omega$ ,	See Figure 17	Full	2.3 V to 2.7 V	0.5			113
Charge injection	$Q_{\mathbb{C}}$	$V_{GEN} = 0,$ $C_L = 0.1 \text{ nF},$	See Figure 21	25°C	2.5 V		1.15		рC
NO OFF capacitance	C <sub>NO(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 15	25°C	2.5 V		4.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 15	25°C	2.5 V		10.5		pF
NO ON capacitance	C <sub>NO(ON)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 15	25°C	2.5 V		17		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 15	25°C	2.5 V		17		pF
Digital input capacitance	C <sub>I</sub>	$V_I = V_+ \text{ or GND},$	See Figure 15	25°C	2.5 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 18	25°C	2.3 V to 2.7 V		320		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 19	25°C	2.3 V to 2.7 V		-81		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 20	25°C	2.3 V to 2.7 V		-61		dB
Supply				•	- I				
Positive supply	oly Switch ON or 2	25°C	2.7 V			1			
current	I <sub>+</sub>	$V_I = V_+ \text{ or GND},$	OFF	Full	2.1 V			10	μΑ

## **ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY<sup>(1)</sup>**

 $V_{+}$  = 1.65 V to 1.95 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST Co	ONDITIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V <sub>COM</sub> , V <sub>NO</sub>					0		V <sub>+</sub>	٧
Peak ON resistance	r <sub>peak</sub>	$0 \le V_{NO} \le V_+,$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	Full	1.65 V			150	Ω
		$V_{NO} = 0 V$ ,		25°C			10	20	
ON-state	_	$I_{COM} = 4 \text{ mA}$	Switch ON,	Full	1.65 V			20	Ω
resistance	r <sub>on</sub>	V <sub>NO</sub> = 1.8 V,	See Figure 13	25°C	1.05 V		17	50	Ω
		$I_{COM} = -4 \text{ mA}$		Full				50	
ON-state resistance match between channels	Δr <sub>on</sub>	$V_{NO} = 1.15 \text{ V},$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	25°C	1.65 V		0.3		Ω
ON-state resistance flatness	r <sub>on(flat)</sub>	$0 \le V_{NO} \le V_+,$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	25°C	1.8 V		140		Ω
NO		$V_{NO} = 0$ to $V_+$ ,	Switch OFF,	25°C		-0.1		0.1	μА
OFF leakage current	I <sub>NO(OFF)</sub>	$V_{COM} = V_+ \text{ to } 0$	See Figure 14	Full	1.95 V	-1		1	
COM		$V_{COM} = 0$ to $V_+$ ,	Switch OFF,	25°C		-0.1		0.1	
OFF leakage current	I <sub>COM(OFF)</sub>	$V_{NO} = V_{+} \text{ to } 0,$	See Figure 14	Full	1.95 V	-1		1	μΑ
NO		$V_{NO} = 0$ to $V_{+}$	Switch ON,	25°C		-0.1		0.1	
ON leakage current	I <sub>NO(ON)</sub>	$V_{COM} = V_{+} \text{ to } 0,$	See Figure 14	Full	1.95 V	-1		1	μΑ
COM		V <sub>NO</sub> = Open,	Switch ON,	25°C		-0.1		0.1	
ON leakage current	I <sub>COM(ON)</sub>	$V_{COM} = 0 \text{ to } V_+,$	See Figure 14	Full	1.95 V	-1		1	μΑ
Digital Control Inpu	uts (IN1, IN2)	) <sup>(2)</sup>							
Input logic high	$V_{IH}$			Full		$V_+ \times 0.75$		5.5	V
Input logic low	$V_{IL}$			Full		0	V.	+×0.25	V
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = 5.5 V or 0		25°C Full	1.95 V			0.1	μА

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

<sup>(2)</sup> All unused digital inputs of the device must be held at V<sub>+</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



## **ELECTRICAL CHARACTERISTICS FOR 1.8-V SUPPLY (continued)**

 $V_{+}$  = 1.65 V to 1.95 V,  $T_{A}$  = -40°C to 85°C (unless otherwise noted)

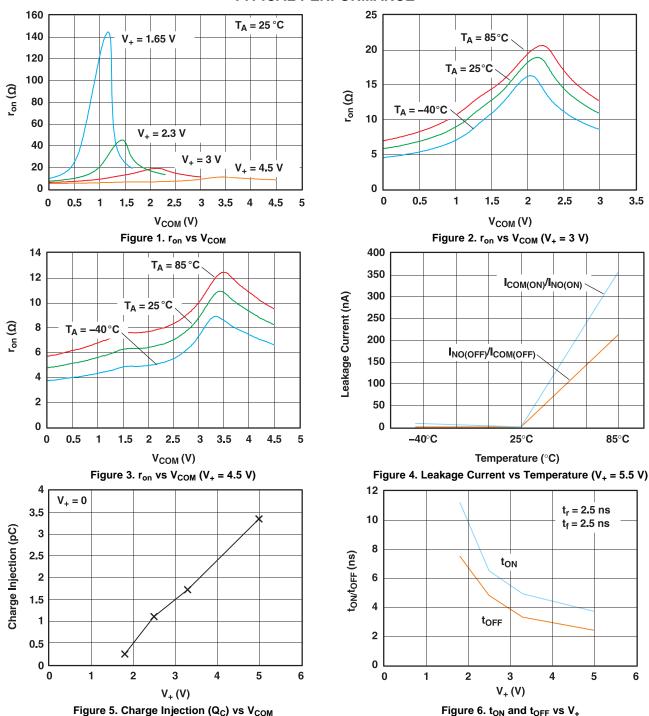
PARAMETER	SYMBOL	TEST CONDITIONS		T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Dynamic		1							
		V CND	0 50 - 5	25°C	1.8 V	5		32	
Turn-on time	t <sub>ON</sub>	$V_{NO} = V_{+} \text{ or GND},$ $R_{L} = 500 \Omega,$	C <sub>L</sub> = 50 pF, See Figure 16	Full	1.65 V to 1.95 V	5		34	ns
		V V · · · OND	0 50 - 5	25°C	1.8 V	3		14	
Turn-off time	t <sub>OFF</sub>	$V_{NO} = V_{+} \text{ or GND},$ $R_{L} = 500 \Omega,$	C <sub>L</sub> = 50 pF, See Figure 16	Full	1.65 V to 1.95 V	3		14.5	ns
Break-before-		V - V	C <sub>L</sub> = 50 pF,	25°C	1.8 V	0.5			Ī
make time	t <sub>BBM</sub>	$V_{NO} = V_+,$ $R_L = 50 \Omega,$	See Figure 17	Full	1.65 V to 1.95 V	0.5			ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $C_L = 0.1 \text{ nF},$	See Figure 21	25°C	1.8 V		0.3		рС
NO OFF capacitance	C <sub>NO(OFF)</sub>	$V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 15	25°C	1.8 V		4.5		pF
COM OFF capacitance	C <sub>COM(OFF)</sub>	$V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 15	25°C	1.8 V		10.5		pF
NO ON capacitance	C <sub>NO(ON)</sub>	$V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 15	25°C	1.8 V		17		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 15	25°C	1.8 V		17		pF
Digital input capacitance	C <sub>I</sub>	$V_I = V_+$ or GND,	See Figure 15	25°C	1.8 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 18	25°C	1.65 V to 1.95 V		341		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch OFF, See Figure 19	25°C	1.65 V to 1.95 V		-81		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , f = 10 MHz,	Switch ON, See Figure 20	25°C	1.65 V to 1.95 V		-61		dB
Supply	•			•					
Positive supply current	I <sub>+</sub>	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	1.95 V			1 10	μΑ

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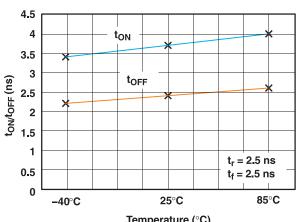


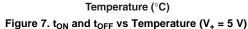
#### **TYPICAL PERFORMANCE**





## **TYPICAL PERFORMANCE (continued)**





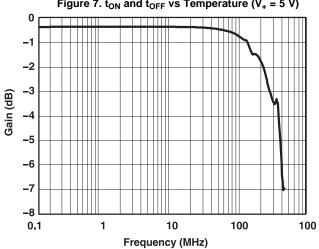


Figure 9. Frequency Response  $(V_+ = 3 V)$ 

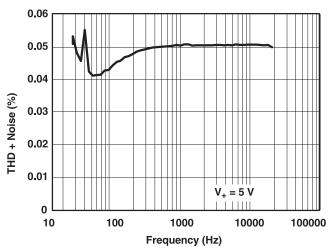


Figure 11. Total Harmonic Distortion vs Frequency  $(V_+ = 5 V)$ 

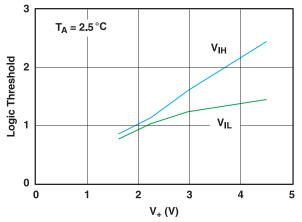


Figure 8. Logic-Level Threshold vs V<sub>+</sub>

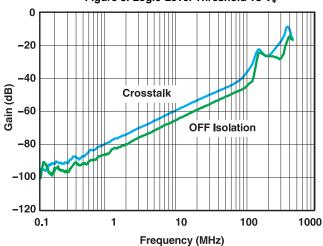


Figure 10. OFF Isolation and Crosstalk vs Frequency (V $_{+}$  = 3 V)

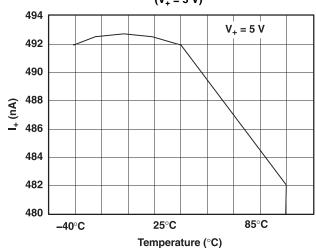


Figure 12. Power-Supply Current vs Temperature  $(V_+ = 5 V)$ 

#### **PIN DESCRIPTION**

PIN NO.	NAME	DESCRIPTION
1	NO0	Normally open
2	NO1	Normally open
3	NO2	Normally open
4	GND	Digital ground
5	IN2	Digital control to connect COM to NO
6	IN1	Digital control to connect COM to NO
7	COM	Common
8	V <sub>+</sub>	Power supply

### PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
V <sub>COM</sub>	Voltage at COM
$V_{NO}$	Voltage at NO
r <sub>on</sub>	Resistance between COM and NC or COM and NO ports when the channel is ON
r <sub>peak</sub>	Peak on-state resistance over a specified voltage range
$\Delta r_{on}$	Difference of ron between channels in a specific device
r <sub>on(flat)</sub>	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
$I_{NO(OFF)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state
I <sub>NO(ON)</sub>	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
I <sub>COM(ON)</sub>	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) open
I <sub>COM(OFF)</sub>	Leakage current measured at the COM port during the power-down condition, $V_{+} = 0$
$V_{IH}$	Minimum input voltage for logic high for the control input (IN)
$V_{IL}$	Maximum input voltage for logic low for the control input (IN)
$V_{I}$	Voltage at the control input (IN)
$I_{IH},\ I_{IL}$	Leakage current measured at the control input (IN)
t <sub>ON</sub>	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning ON.
t <sub>OFF</sub>	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM or NO) signal when the switch is turning OFF.
t <sub>BBM</sub>	Break-before-make time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
Q <sub>C</sub>	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$ , $C_L$ is the load capacitance and $\Delta V_{COM}$ is the change in analog output voltage.
C <sub>NO(OFF)</sub>	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C <sub>NO(ON)</sub>	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
C <sub>COM(ON)</sub>	Capacitance at the COM port when the corresponding channel (COM to NO) is ON
$C_{COM(OFF)}$	Capacitance at the COM port when the corresponding channel (COM to NO) is OFF
$C_{l}$	Capacitance of control input (IN)
O <sub>ISO</sub>	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
X <sub>TALK</sub>	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
I <sub>+</sub>	Static power-supply current with the control (IN) pin at V <sub>+</sub> or GND



#### PARAMETER MEASUREMENT INFORMATION

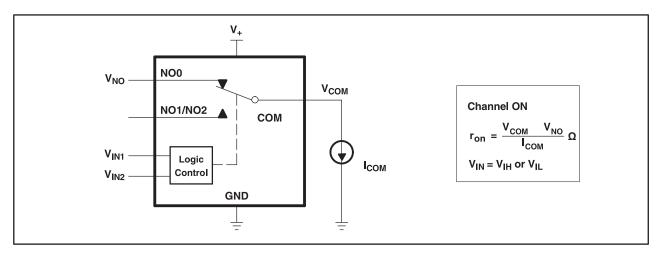


Figure 13. ON-State Resistance (ron)

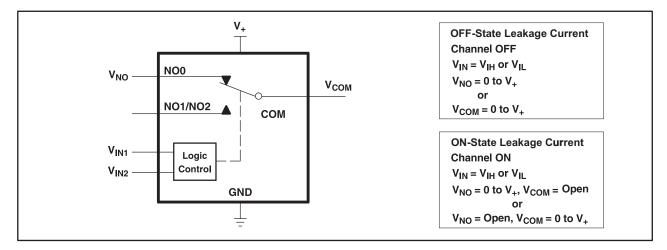


Figure 14. ON- and OFF-State Leakage Current (I<sub>COM(ON)</sub>, I<sub>COM(OFF)</sub>, I<sub>NO(ON)</sub>, I<sub>NO(OFF)</sub>)

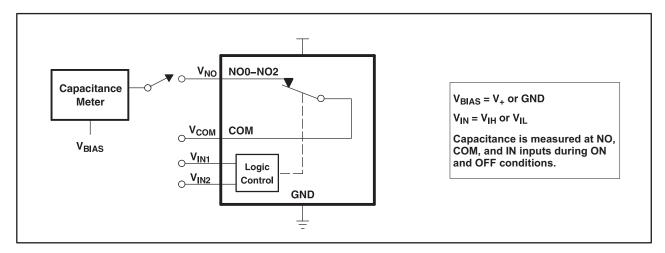
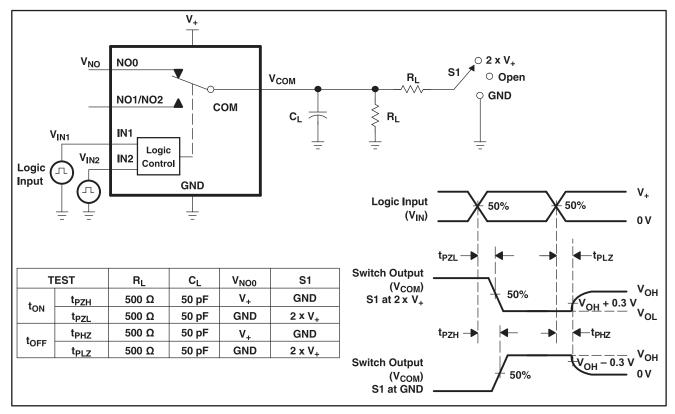


Figure 15. Capacitance (C<sub>I</sub>, C<sub>COM(ON)</sub>, C<sub>NO(OFF)</sub>, C<sub>COM(OFF)</sub>, C<sub>NO(ON)</sub>)

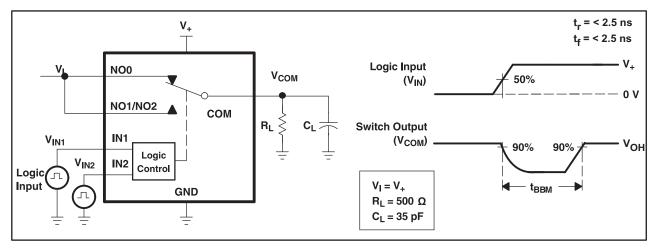


### PARAMETER MEASUREMENT INFORMATION (continued)



- A. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.
- B. C<sub>L</sub> includes probe and jig capacitance.

Figure 16. Turn-On (ton) and Turn-Off Time (toff)



- A. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_t < 5$  ns.
- B. C<sub>L</sub> includes probe and jig capacitance.

Figure 17. Break-Before-Make Time (t<sub>BBM</sub>)



## PARAMETER MEASUREMENT INFORMATION (continued)

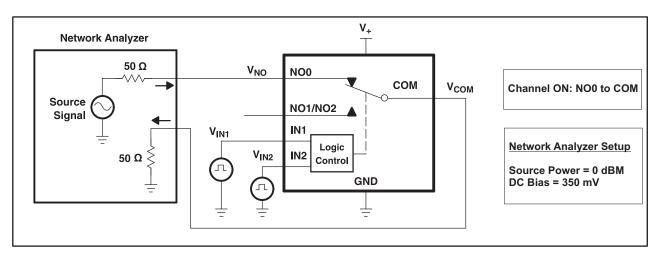


Figure 18. Bandwidth (BW)

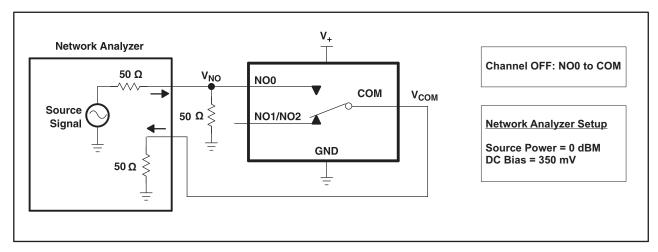


Figure 19. OFF Isolation (O<sub>ISO</sub>)

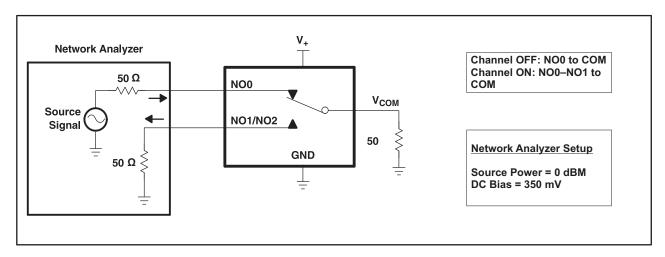
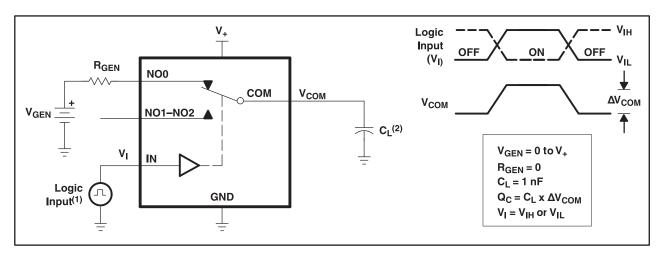


Figure 20. Crosstalk (X<sub>TALK</sub>)



## PARAMETER MEASUREMENT INFORMATION (continued)



- A. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r < 5$  ns,  $t_f < 5$  ns.
- B. C<sub>L</sub> includes probe and jig capacitance.

Figure 21. Charge Injection (Q<sub>C</sub>)

## **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A3357DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
TS5A3357DCUR	VSSOP	DCU	8	3000	178.0	9.5	2.25	3.35	1.05	4.0	8.0	Q3
TS5A3357DCURG4	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
TS5A3357DCUT	VSSOP	DCU	8	250	178.0	9.5	2.25	3.35	1.05	4.0	8.0	Q3

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\*All dimensions are nominal

7 till difficilities die fremman							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A3357DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A3357DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A3357DCURG4	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A3357DCUT	VSSOP	DCU	8	250	202.0	201.0	28.0

# DCU (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



NOTES:

- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-187 variation CA.



DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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